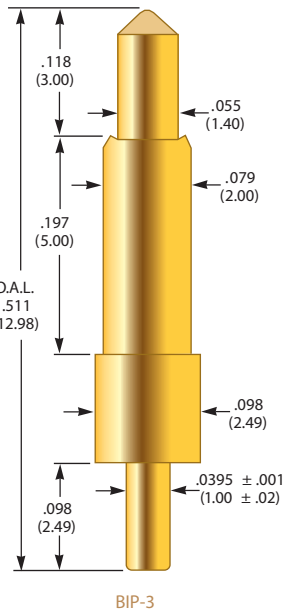
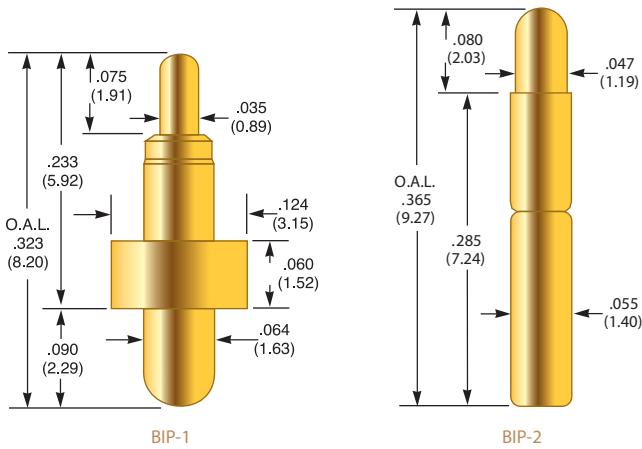


TO ORDER, CALL 909-625-9390



- Applications for BIP Series**
 BIP Series probes are used in battery charger or electronic device applications such as:
1. Camcorders
 2. Circuit board to board docking stations
 3. Cellular Phones
 4. 2-way radios
 5. Computer docking stations
 6. Cordless phones
 7. Chargers
 8. InkJet Printers
 9. Notebook and laptop computers
 10. AC/DC power supplies

- Benefits and Features:**
1. Low resistance (average 16 milliohms)
 2. Better contact than nickel-plated strip contacts
 3. Maintains high compliancy
 4. Less susceptible to damage
 5. Can accommodate up to .025" subsurface battery mating contact
 6. Longer life than conventional interconnects

Probe Specifications	BIP-1	BIP-2	BIP-3
Mechanical			
Full Travel:	.075 (1.91)	.050 (1.27)	.100 (2.54)
Recommended Travel:	.050 (1.27)	.050 (1.27)	.060 (1.52)
Mechanical Life Exceeds:	250 x10 ³ cycles	1 x10 ⁶ cycles	250 x10 ³ cycles
Operating Temperature:	-55°C to +150°C	-55°C to +150°C	-55°C to +105°C
Consult factory for other temperature requirements.			
Electrical (Static Conditions)	5 amps d.c. max	5 amps d.c. max	5 amps d.c. max
Maximum Current Rating (Non-inductive DC)			
Average Probe Resistance	16 mΩ	30 mΩ	30 mΩ
Materials and Finishes			
Plunger:	Hard nickel over beryllium copper, gold plated	Hard nickel over beryllium copper, gold plated	Hard nickel over brass, gold plated
Barrel:	Hard nickel over brass, gold plated	Hard nickel over nickel silver, gold plated	Hard nickel over brass, gold plated
Spring:			
Standard:	Stainless steel, silver plated	Stainless steel, silver plated	Stainless Steel, silver plated
Alternate:	Consult factory	Consult factory	Music wire, silver plated
Mounting Hole Size:	.067 (1.70) min.	.053 (1.35)	.043 (1.09) min

Spring Force in oz. (grams)	Spring Type		
	Preload	Recommended Travel	
BIP-1 Standard	1.39 (39.44)	3.50 (99.31)	
BIP-2 Standard	1.10 (31.2)	3.85 (109)	
BIP-3 Standard	0.40 (11.35)	1.14 (32.35)	
BIP-3 Alternate	1.0 (28.38)	3.0 (85.13)	
Tip Styles	J	J	B

Termination

- BIP-1: Soldered into PCB
- BIP-2: Press Fit
- BIP-3: Soldered into PCB